

# Jiankui Chen

## List of Publications by Year in descending order

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14  
papers

226  
citations

1307594

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1058476

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14  
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docs citations

14  
times ranked

298  
citing authors

#	ARTICLE	IF	CITATIONS
1	Accurate Stereo-Vision-Based Flying Droplet Volume Measurement Method. IEEE Transactions on Instrumentation and Measurement, 2022, 71, 1-16.	4.7	7
2	Path Tracking Control of Skid-steered Mobile Robot on the Slope Based on Fuzzy System and Model Predictive Control. International Journal of Control, Automation and Systems, 2022, 20, 1365-1376.	2.7	8
3	Positioning Error Limit for the Last Droplet Deposition into a Microcavity in the Manufacture of Printed OLEDs. Langmuir, 2021, 37, 9396-9404.	3.5	6
4	Web Tension Estimation by Local Contact Force Measurement in Roll-to-Roll Manufacturing. International Journal of Precision Engineering and Manufacturing, 2020, 21, 2067-2075.	2.2	1
5	Polygonal-feature-based shape context for flexible surface vision positioning. Measurement Science and Technology, 2019, 30, 055403.	2.6	4
6	Theoretical and Experimental Studies of Chip Position Drift in Motional Chip Placement Process. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1888-1896.	2.5	1
7	High-Efficiency Revolving-Turret Chip Transferring Technology for Flip Chip Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 154-164.	2.5	14
8	Theoretical and Experimental Studies of Competing Fracture for Flexible Chip-Adhesive-Substrate Composite Structure. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 57-64.	2.5	12
9	Conformal Peeling of Device-on-Substrate System in Flexible Electronic Assembly. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1496-1506.	2.5	14
10	High-rate roll-to-roll stack and lamination of multilayer structured membrane electrode assembly. Journal of Manufacturing Processes, 2016, 23, 175-182.	5.9	26
11	Analytical investigation on thermal-induced warpage behavior of ultrathin chip-on-flex (UTCOF) assembly. Science China Technological Sciences, 2016, 59, 1646-1655.	4.0	5
12	Vacuum-based picking-up of thin chip from adhesive tape. Journal of Adhesion Science and Technology, 2015, 29, 1315-1329.	2.6	14
13	Highly sensitive, temperature-dependent gas sensor based on hierarchical ZnO nanorod arrays. Journal of Materials Chemistry C, 2015, 3, 11397-11405.	5.5	105
14	Temperature-dependent orientation study of the initial growth of pentacene on amorphous SiO <sub>2</sub> by molecular dynamics simulations. Journal of Crystal Growth, 2015, 429, 35-42.	1.5	9